

**ABSTRACT OF THE DISCLOSURE:**

**TITLE:       SYSTEM FOR TESTING A GROUP OF IC-CHIPS  
              HAVING A CHIP HOLDING SUBASSEMBLY  
              THAT IS BUILT-IN AND LOADED/UNLOADED  
              AUTOMATICALLY**

          An electromechanical system for testing IC-chips includes a chip holding subassembly which has sockets for holding a group of IC-modules that include the IC-chips; a moving mechanism for automatically moving  
5   the chip holding subassembly from a load position in the system to a test position in the system, and visa-versa; a temperature control mechanism which contacts the IC-modules on the chip holding subassembly only when that subassembly is at the test position; and a chip handler  
10   mechanism for automatically moving the IC-modules into and out of the sockets, when the chip holding subassembly is at the load position. At the test position, the temperature control mechanism contacts the IC-modules to control their temperature. At the load position, the  
15   chip handler mechanism automatically unloads one group of IC-modules from the sockets on the chip holding subassembly and automatically loads another group of the IC-modules into the sockets.